Annexure – II

(On Stamp Paper of Rs. 500/-)

**Indemnity Bond**

 I, Mr. / Ms. \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_.

Age\_\_\_\_\_\_\_\_ Year, at present residing at \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ (current address), my permanent address is \_\_\_\_\_\_\_\_\_\_ do hereby state on solemn affirmation on this \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ (day), of \_\_\_\_\_\_\_ (month) \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ (year), as under :

1. I was admitted in First Year / Direct Second Year (Name of branch) Engineering through CAP at (name of the college) institute in the A.Y. \_\_\_\_\_\_\_, I was studying in final year of (name of branch) engineering, In the A/Y 2021-22, A/Y 2022-23 & A/Y 2023-24, I had filled the application on MahaDBT portal under scheme named as Post Martric Scholarship/Free ship applicable to SC category students for reimbursement of fees for the year 2021-22, 2022-23 & 2023-24 along with all necessary documents. Said application is scrutinized by the concerned authorities and approved / under approval process on MahaDBT portal
2. According to the Central Government guidelines, 60% of the SC Scholarship amount will be credited to my savings account mentioned in the Scholarship application form.
3. The 60% of the Scholarship amount that is likely to be deposited in my saving account is as under.
4. For the year 2021-22 = Rs. ………………
5. For the year 2022-23 = Rs. ………………
6. For the year 2023-24 = Rs. ………………

 Total = Rs ……………….

1. In view of central government guidelines, I abide to transfer the 60% Scholarship amount received from the Government in my bank account to the college within 7 days from the receipt of such amount in my bank account.
2. Since I am not aware about when the 60% Scholarship amount will be transferred by the Government in my bank account, whenever I gets the Scholarship amount I will solely liable the consequences and effects arise due to non payment.
3. I indemnify the (Name of College), from any type of loss or damage caused to the college in legal proceedings due to my indemnity bond given herein above regarding payment of Scholarship amount to the college.
4. I shall communicate to the college about change of my present address, mobile number and email ID, if any, from time to time.

I here declare the above information given by me is true to the best of my knowledge and belief.

Date :\_\_\_\_\_\_\_

Place : \_\_\_\_\_\_\_ \_\_\_\_\_\_\_\_

 Signature of Student

 Name of the Student \_\_\_\_\_\_\_\_\_\_\_\_

 Department : \_\_\_\_\_\_\_\_\_\_\_

 Engineering :

Witness :

1. Mr. / Ms. \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ \_\_\_\_\_\_\_\_\_\_\_\_

Sign

1. Mr. / Ms. \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ \_\_\_\_\_\_\_\_\_\_\_\_

Sign